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Sponsored by: IEEE Industrial Electronics Society, Yunnan University, China

The 23rd IEEE International Conference on Industrial Informatics INDIN 2025 will be held from Saturday to Tuesday, July 12-15, 2025, Kunming, China.

INDIN is a flagship conference of IEEE Industrial Electronics Society providing a forum for presentation and discussion of the state-of-art and future perspectives of industrial information technologies. This is the 23rd edition of the conference, with recent previous editions being hosted as follows: Helsinki-Espoo, Finland (2019), Coventry, UK (2020), Palma de Mallorca/Online, Spain (2021), Perth, Australia (2022), Lemgo, Germany (2023), Beijing, China (2024). IEEE INDIN 2025 aims to provide an international platform for cutting edge research and professional interactions for the development of industrial information technologies. Industry experts, researchers and academics are gathering together to share ideas and experiences surrounding frontier technologies, breakthroughs, innovative solutions, research results, as well as initiatives related to industrial informatics and their applications.

A number of Special Sections in leading IEEE Journals such as TII, TICPS, OJIES and JESTIE, elaborating conference topics will be generated after the event. Authors of accepted papers, with excellent reviews, will be invited to submit an improved version of their papers for further consideration.

Starting from this year's edition there is the possibility to submit **Work-in-Progress (WiP)** papers. They are up to 4-page contributions presenting preliminary research findings or innovative concepts not fully developed. WiPs are included in IEEEExplore as other papers.

Topics within the scope (but not limited to):

- Embodied Intelligence, Industrial AI, Industrial Agents, Edge AI, and Runtime Intelligence
- Software Technology, Architecture, and Engineering in Industrial Applications
- Data Collection, Analytics, and Management in Industrial Applications
- User Experience and Human Factors in Industrial Systems
- Industrial Cloud, Edge, and Fog Computing
- Industrial Wired and Wireless Communications
- Industrial Cyber-Physical Systems and Digital Twin
- Modeling, Monitoring, Diagnostics, Control, Operation, and Optimization of Automation Systems
- Control, Communication, and Computing Co-design
- Reliability, Security, Safety, and Resilience of Industrial Systems
- Vertical Applications of Industrial Informatics in Building Automation, Process Automation, Factory Automation, Robotics, Energy Systems, Power Grids, Agriculture, Healthcare, Vehicles, Transportation Systems, etc.
- Standards, Education, and Ethic Issues

Featured Programs (out of technical tracks):

- Best Presentation Award
- Students & Young Professionals Prize
- Invited Presentation of IES Journal Papers
- Hackathons and Competitions
- Industry Forum
- Exhibition of sponsors
- Women in Engineering Forum
- INTEROP Plugfest

Important Dates:

Special Session Proposal: Jan. 15, 2025
 Full Paper Submission: Feb. 15, 2025
 Decision Notification: Apr. 15, 2025
 WiP Paper Submission: Apr. 30, 2025
 WiP Decision Notification: May 30, 2025
 Early Registration: Apr. 30, 2025

Kunming, the capital of Yunnan Province, China, is often called the "Spring City" due to its year-round spring-like climate. It is a vibrant city with a rich history, splendid culture, pleasant weather, and abundant tourism resources.

